

## QM6015B-VB Datasheet

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	(Ω) I <sub>D</sub> (A) <sup>a</sup> Q <sub>g</sub> (Typ.			
- 60	0.019 at V <sub>GS</sub> = - 10 V	- 80	76 nC		
	0.025 at V <sub>GS</sub> = - 4.5 V	- 70	70110		

#### **FEATURES**

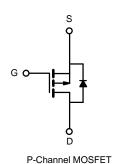
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	- 60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		
	T <sub>C</sub> = 25 °C		- 80 <sup>a</sup>		
Continuous Drain Current (T = $150 ^{\circ}$ C)	T <sub>C</sub> = 70 °C		- 70	1	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	9.2 <sup>b</sup>	A	
	T <sub>A</sub> = 70 °C		- 8.1 <sup>b</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	- 150	1	
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	- 45		
Single Pulse Avalanche Energy	L = 0.1 IIIH	E <sub>AS</sub>	101	mJ	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	1	69 <sup>a</sup>		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.1 <sup>b</sup>	- A	
	T <sub>C</sub> = 25 °C		104.2 <sup>a</sup>		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	р	66.7 <sup>a</sup>	10/	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b</sup>	W	
	T <sub>A</sub> = 70 °C		2 <sup>b</sup>	1	
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	33	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.98	1.2	0/11	

Notes:

a. Based on T<sub>C</sub> = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C,	unless othe	erwise noted)					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = - 250 μΑ		68		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	5		- 5.2			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1		- 3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zana Osta Malla en Deria Orana el		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS}$ = - 60 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C			- 10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.019		Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.025			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A	20			S	
Dynamic <sup>b</sup>						1	
Input Capacitance	C <sub>iss</sub>			3500		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz		390			
Reverse Transfer Capacitance	C <sub>rss</sub>			290			
	Q <sub>g</sub> Q <sub>gs</sub>	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -55$ A		76		nC	
Total Gate Charge		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 55 A		38			
Gate-Source Charge				16			
Gate-Drain Charge	Q <sub>gd</sub>			19			
Gate Resistance	Rg	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 2 V, $R_L$ = 2 $\Omega$		7	15	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		70	110		
Fall Time	t <sub>f</sub>			40	60		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			- 69	٨	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 150	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 30 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			45	68	ns	
Body Diode Reverse Recovery Charge				59	120	nC	
Reverse Recovery Fall Time	ta	I <sub>F</sub> = - 50 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C		29			
Reverse Recovery Rise Time	t <sub>b</sub>			16		ns	

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

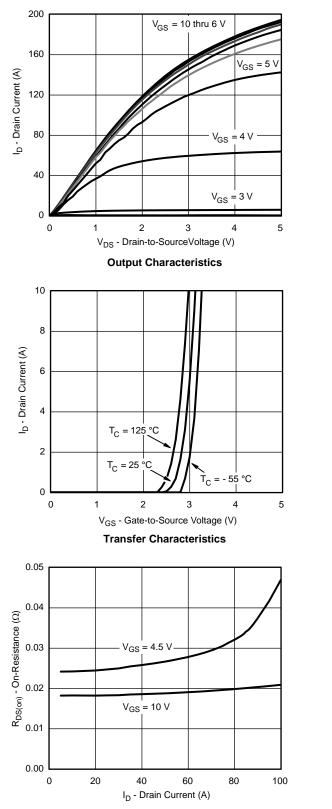
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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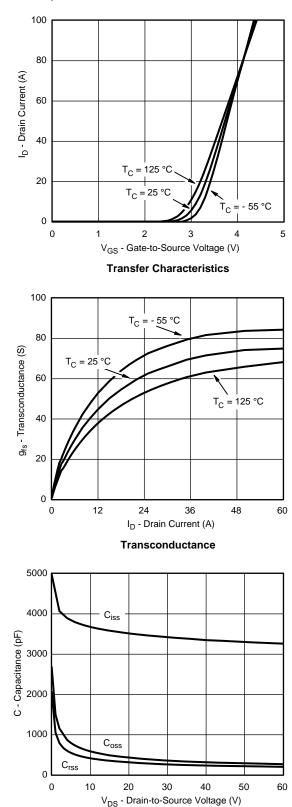
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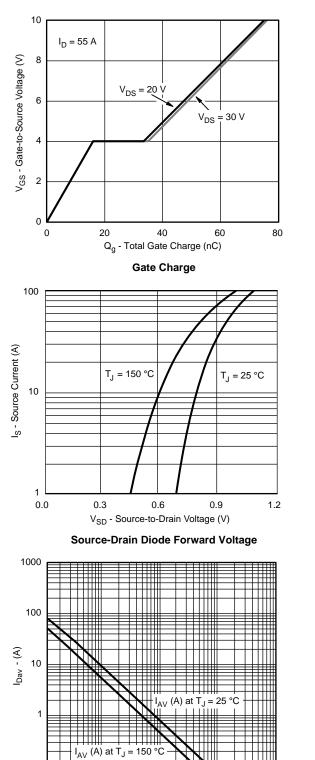
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

**On-Resistance vs. Drain Current** 



Capacitance





#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

 $\label{eq:Tin-s} T_{\text{in}} \text{-} (s)$  Single Pulse Avalanche Current Capability vs. Time

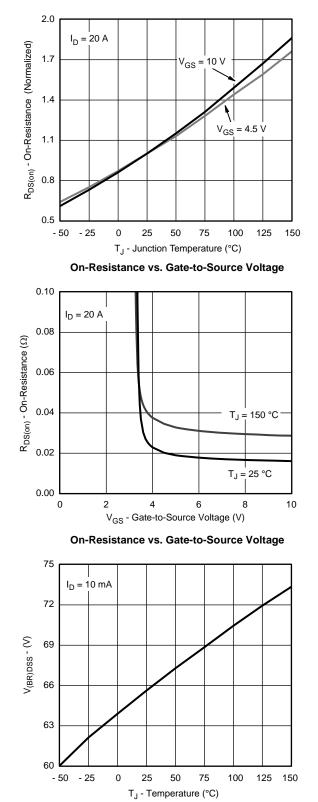
0.01

0.1

1

11111

0.001

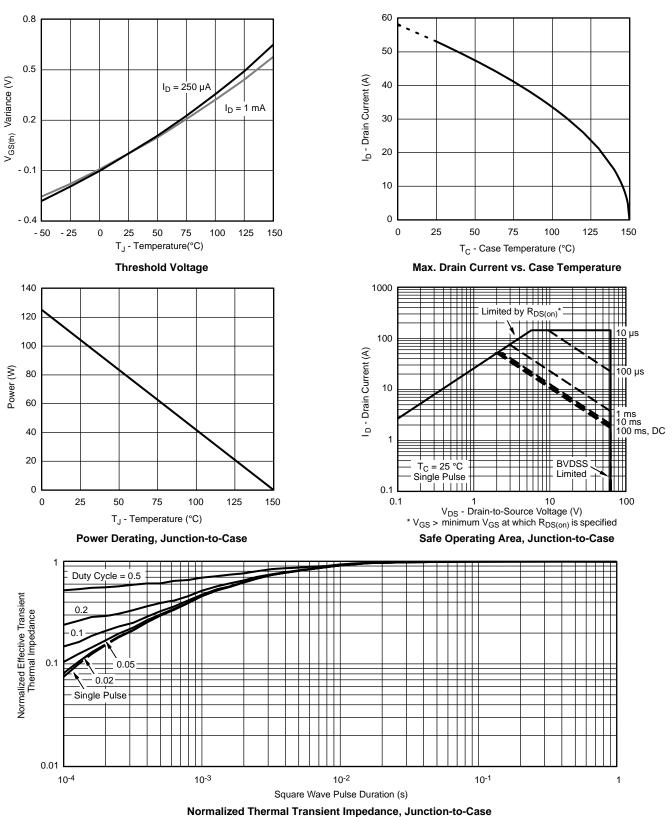


Drain-Source Breakdown Voltage vs. Junction Temperature

0.1

0.0001

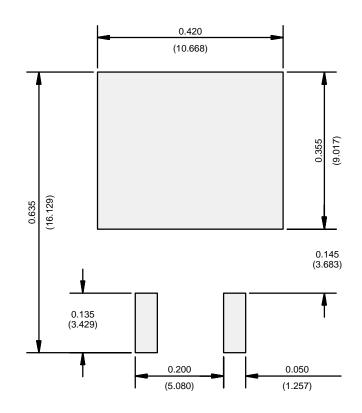




#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



### **RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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